## The influence of native oxides on physicochemical properties of p-type GaN(0001) and N-rich GaNAs(0001) surface

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The GaN-based semiconductors attract much attention in the electronic industry because of wide, direct energy band gap (3.4 eV) and good thermal conductivity [1]. These materials have a huge potential to fabricate short-wavelength optoelectronics as well as high-power and -frequency devices [2]. Moreover, GaN-based materials attract great interests due to possibility of bands structure modification by replacing one of its components. For example, substituting the nitrogen with an arsenic atom leads to a decrease of the band gap [3]. Optical measurements show that the band gap of GaNAs alloys is reduced with increase of the As content [4], which was also well explained by the band anticrossing model (BAC) [3].

A native oxide layer and other contaminants which appear after air exposure of the sample, acts as a barrier at the metal/GaN interface [5] and can reduce a potential device performance. To remove oxide and carbon coverage different surface treatments need to be introduced. Our studies show change of physicochemical properties of p-GaN(0001) and GaN<sub>0.996</sub>As<sub>0.004</sub> (0001) after air exposure and different surface treatments (HCl treatment, UHV annealing, Ar<sup>+</sup> bombardment). The investigated samples were grown by molecular beam epitaxy (MBE) and studied under ultrahigh vacuum (UHV) by means of X-ray photoelectron spectroscopy (XPS). The experiment shows that applied cleaning techniques allow to obtain the surface with a trace amount of oxygen and carbon. Our research indicates that air exposure shifts valence band maximum (VBM) to 2.7 eV for p-GaN(0001) and to 2.6 eV for GaN<sub>0.996</sub>As<sub>0.004</sub> (0001), which greatly corresponds with the theoretical study by Segev and Van de Walle [6]. Our research indicates that the VBM lies at positions of 1.6 eV and 2.1 eV below the Fermi level ( $E_F$ ) for cleaned p-GaN and GaN(As) samples, respectively. This shows that small amount of As atoms incorporated into the GaN matrix leads to the VBM shift by 0.6 eV towards the  $E_F$  which is in line with the BAC model [3].

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